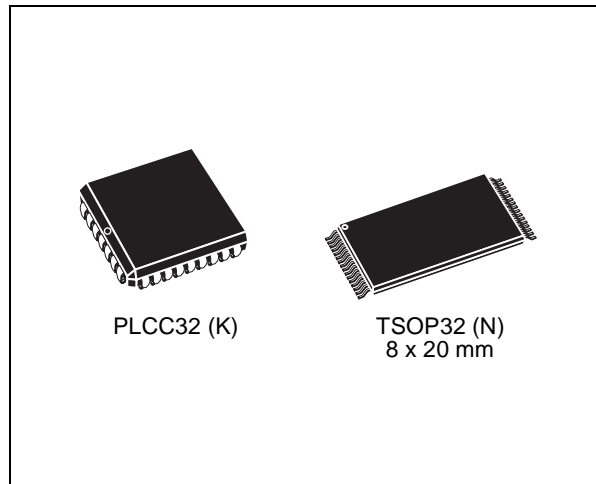




## 4 Mbit (512Kb x8) Low Voltage OTP EPROM

NOT FOR NEW DESIGN

- 3V to 3.6V SUPPLY VOLTAGE in READ OPERATION
- ACCESS TIME: 120ns
- LOW POWER CONSUMPTION:
  - Active Current 15mA at 5MHz
  - Standby Current 20µA
- PROGRAMMING VOLTAGE: 12.75V ± 0.25V
- PROGRAMMING TIMES:
  - Typical 48sec. (PRESTO II Algorithm)
  - Typical 27sec. (On-Board Programming)
- PIN COMPATIBLE with the 4 Mbit, Single Voltage Flash Memory
- ELECTRONIC SIGNATURE
  - Manufacturer Code: 20h
  - Device Code: B4h



### DESCRIPTION

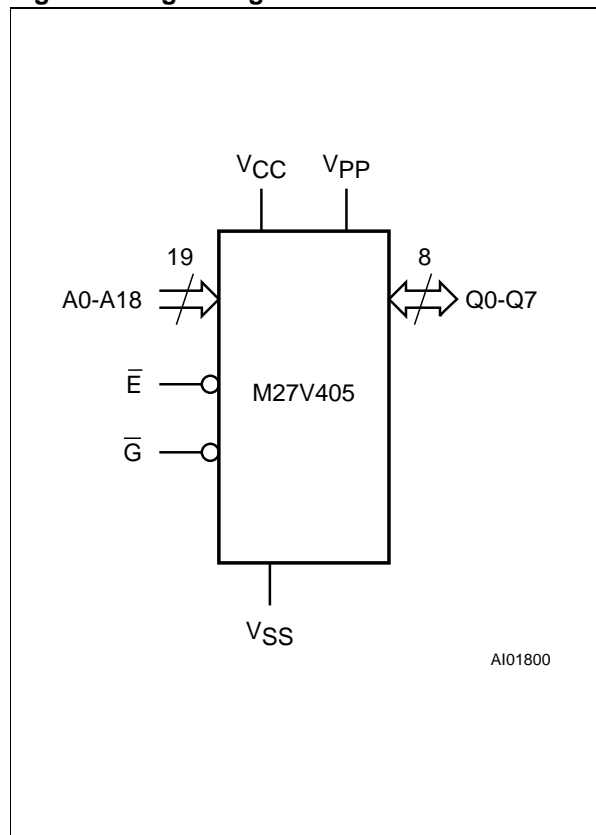
The M27V405 is a low voltage 4 Mbit EPROM offered in the OTP range (one time programmable). It is ideally suited for microprocessor systems requiring large data or program storage and is organised as 524,288 by 8 bits.

The M27V405 operates in the read mode with a supply voltage as low as 3V. The decrease in operating power allows either a reduction of the size of the battery or an increase in the time between battery recharges.

The M27V405 is pin compatible with the industry standard 4 Mbit, single voltage Flash Memory. It can be considered as a Flash Low Cost solution for production quantities.

The M27V405 can also be operated as a standard 4 Mbit OTP EPROM (similar to M27C405) with a 5V power supply. The M27V405 is offered in PLCC32 and TSOP32 (12 x 20 mm) packages.

Figure 1. Logic Diagram



## M27V405

Figure 2A. LCC Connections

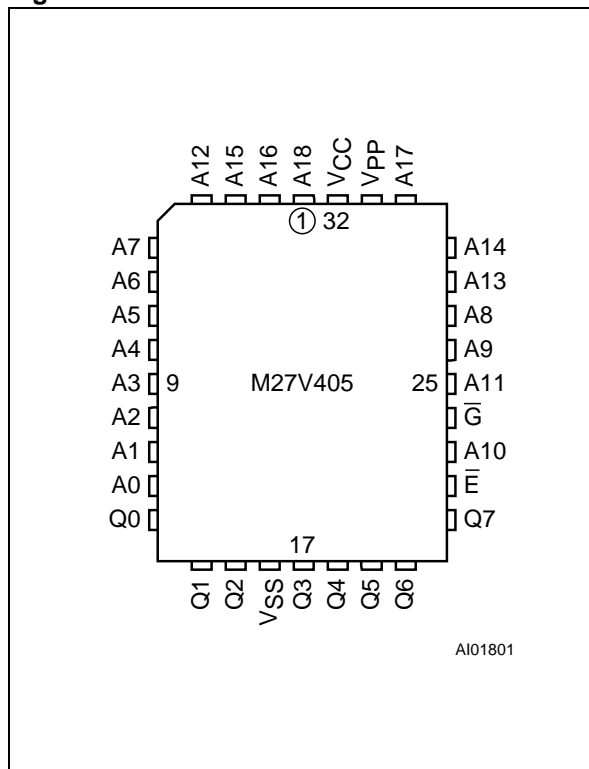


Figure 2B. TSOP Connections

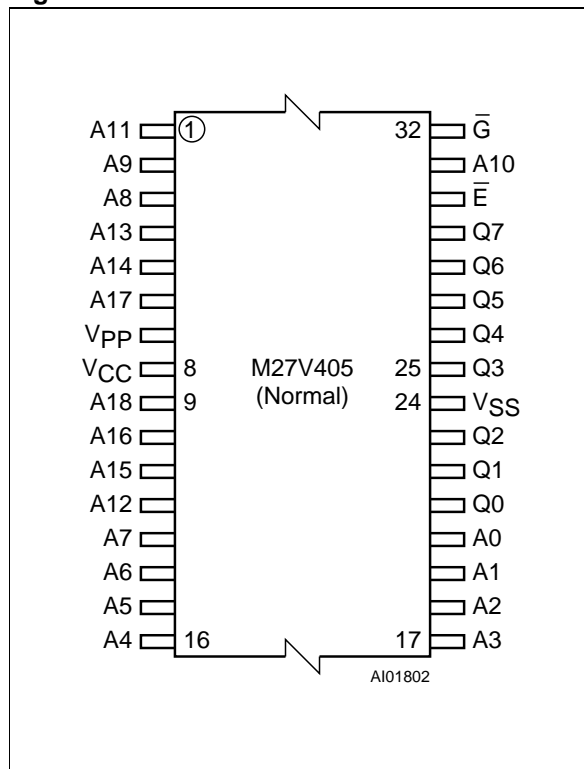


Table 1. Signal Names

A0-A18	Address Inputs
Q0-Q7	Data Outputs
$\bar{E}$	Chip Enable
$\bar{G}$	Output Enable
V <sub>PP</sub>	Program Supply
V <sub>CC</sub>	Supply Voltage
V <sub>SS</sub>	Ground

### DEVICE OPERATION

The modes of operations of the M27V405 are listed in the Operating Modes table. A single power supply is required in the read mode. All inputs are TTL levels except for V<sub>pp</sub> and 12V on A9 for Electronic Signature.

#### Read Mode

The M27V405 has two control functions, both of which must be logically active in order to obtain data at the outputs. Chip Enable ( $\bar{E}$ ) is the power control and should be used for device selection. Output Enable ( $\bar{G}$ ) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that the addresses are stable, the address access time (t<sub>AVQV</sub>) is equal to the delay from  $\bar{E}$  to output (t<sub>ELQV</sub>). Data is available at the output after a delay of t<sub>GLQV</sub> from the falling edge of  $\bar{G}$ , assuming that  $\bar{E}$  has been low and the addresses have been stable for at least t<sub>AVQV</sub>-t<sub>GLQV</sub>.

**Table 2. Absolute Maximum Ratings (1)**

Symbol	Parameter	Value	Unit
T <sub>A</sub>	Ambient Operating Temperature (3)	-40 to 125	°C
T <sub>BIAS</sub>	Temperature Under Bias	-50 to 125	°C
T <sub>STG</sub>	Storage Temperature	-65 to 150	°C
V <sub>IO</sub> (2)	Input or Output Voltage (except A9)	-2 to 7	V
V <sub>CC</sub>	Supply Voltage	-2 to 7	V
V <sub>A9</sub> (2)	A9 Voltage	-2 to 13.5	V
V <sub>PP</sub>	Program Supply Voltage	-2 to 14	V

Note: 1. Except for the rating "Operating Temperature Range", stresses above those listed in the Table "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

2. Minimum DC voltage on Input or Output is -0.5V with possible undershoot to -2.0V for a period less than 20ns. Maximum DC voltage on Output is V<sub>CC</sub> +0.5V with possible overshoot to V<sub>CC</sub> +2V for a period less than 20ns.
3. Depends on range.

**Table 3. Operating Modes**

Mode	$\bar{E}$	$\bar{G}$	A9	V <sub>PP</sub>	Q7-Q0
Read	V <sub>IL</sub>	V <sub>IL</sub>	X	V <sub>CC</sub> or V <sub>SS</sub>	Data Out
Output Disable	V <sub>IL</sub>	V <sub>IH</sub>	X	V <sub>CC</sub> or V <sub>SS</sub>	Hi-Z
Program	V <sub>IL</sub> Pulse	V <sub>IH</sub>	X	V <sub>PP</sub>	Data In
Verify	V <sub>IH</sub>	V <sub>IL</sub>	X	V <sub>PP</sub>	Data Out
Program Inhibit	V <sub>IH</sub>	V <sub>IH</sub>	X	V <sub>PP</sub>	Hi-Z
Standby	V <sub>IH</sub>	X	X	V <sub>CC</sub> or V <sub>SS</sub>	Hi-Z
Electronic Signature	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>ID</sub>	V <sub>CC</sub>	Codes

Note: X = V<sub>IH</sub> or V<sub>IL</sub>, V<sub>ID</sub> = 12V ± 0.5V.

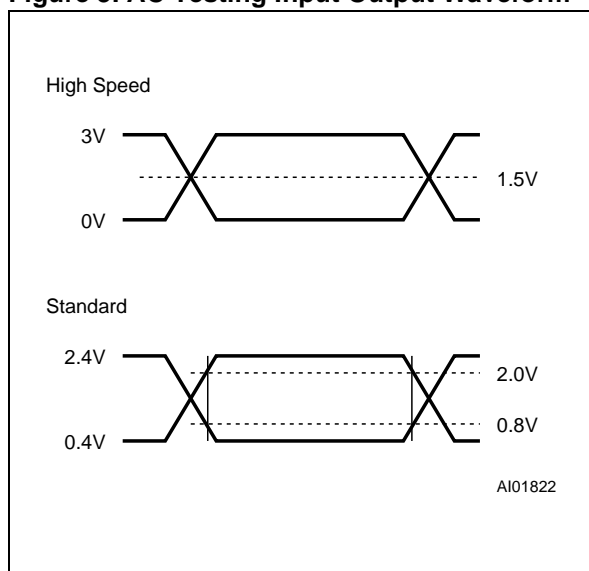
**Table 4. Electronic Signature**

Identifier	A0	Q7	Q6	Q5	Q4	Q3	Q2	Q1	Q0	Hex Data
Manufacturer's Code	V <sub>IL</sub>	0	0	1	0	0	0	0	0	20h
Device Code	V <sub>IH</sub>	1	0	1	1	0	1	0	0	B4h

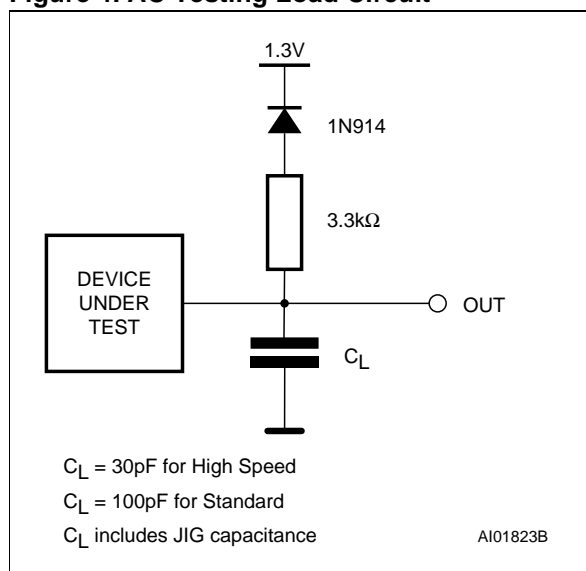
**Table 5. AC Measurement Conditions**

	High Speed	Standard
Input Rise and Fall Times	≤ 10ns	≤ 20ns
Input Pulse Voltages	0 to 3V	0.4V to 2.4V
Input and Output Timing Ref. Voltages	1.5V	0.8V and 2V

**Figure 3. AC Testing Input Output Waveform**



**Figure 4. AC Testing Load Circuit**



**Table 6. Capacitance (1) (TA = 25 °C, f = 1 MHz)**

Symbol	Parameter	Test Condition	Min	Max	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 0V		6	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 0V		12	pF

Note: 1. Sampled only, not 100% tested.

**Standby Mode**

The M27V405 has a standby mode which reduces the active current from 15mA to 20µA with low voltage operation V<sub>CC</sub> ≤ 3.6V, see Read Mode DC Characteristics Table for details. The M27V405 is placed in the standby mode by applying a CMOS high signal to the  $\bar{E}$  input. When in the standby mode, the outputs are in a high impedance state, independent of the  $\bar{G}$  input.

**Two Line Output Control**

Because OTP EPROMs are usually used in larger memory arrays, this product features a 2 line control function which accommodates the use of multiple memory connection. The two line control function allows:

- a. the lowest possible memory power dissipation,
- b. complete assurance that output bus contention will not occur.

For the most efficient use of these two control lines,  $\bar{E}$  should be decoded and used as the primary device selecting function, while  $\bar{G}$  should be made a common connection to all devices in the array and connected to the  $\overline{READ}$  line from the system control bus. This ensures that all deselected memory devices are in their low power standby mode and that the output pins are only active when data is required from a particular memory device.

**Table 7. Read Mode DC Characteristics (1)**(T<sub>A</sub> = 0 to 70°C, -20 to 70°C, -20 to 85°C or -40 to 85°C; V<sub>CC</sub> = 3.3V ± 10%; V<sub>PP</sub> = V<sub>CC</sub>)

Symbol	Parameter	Test Condition	Min	Max	Unit
I <sub>LI</sub>	Input Leakage Current	0V ≤ V <sub>IN</sub> ≤ V <sub>CC</sub>		±10	μA
I <sub>LO</sub>	Output Leakage Current	0V ≤ V <sub>OUT</sub> ≤ V <sub>CC</sub>		±10	μA
I <sub>CC</sub>	Supply Current	$\bar{E} = V_{IL}, \bar{G} = V_{IL}, I_{OUT} = 0mA,$ f = 5MHz, V <sub>CC</sub> ≤ 3.6V		15	mA
I <sub>CC1</sub>	Supply Current (Standby) TTL	$\bar{E} = V_{IH}$		1	mA
I <sub>CC2</sub>	Supply Current (Standby) CMOS	$\bar{E} > V_{CC} - 0.2V, V_{CC} \leq 3.6V$		20	μA
I <sub>PP</sub>	Program Current	V <sub>PP</sub> = V <sub>CC</sub>		10	μA
V <sub>IL</sub>	Input Low Voltage		-0.3	0.8	V
V <sub>IH</sub> (2)	Input High Voltage		2	V <sub>CC</sub> + 1	V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2.1mA		0.4	V
V <sub>OH</sub>	Output High Voltage TTL	I <sub>OH</sub> = -400μA	2.4		V
	Output High Voltage CMOS	I <sub>OH</sub> = -100μA	V <sub>CC</sub> - 0.7V		V

Note: 1. V<sub>CC</sub> must be applied simultaneously with or before V<sub>PP</sub> and removed simultaneously or after V<sub>PP</sub>.2. Maximum DC voltage on Output is V<sub>CC</sub> + 0.5V.**Table 8A. Read Mode AC Characteristics (1)**(T<sub>A</sub> = 0 to 70°C, -20 to 70°C, -20 to 85°C or -40 to 85°C; V<sub>CC</sub> = 3.3V ± 10%; V<sub>PP</sub> = V<sub>CC</sub>)

Symbol	Alt	Parameter	Test Condition	M27V405				Unit
				-120		-150		
				Min	Max	Min	Max	
t <sub>AVQV</sub>	t <sub>ACC</sub>	Address Valid to Output Valid	$\bar{E} = V_{IL}, \bar{G} = V_{IL}$		120		150	ns
t <sub>ELQV</sub>	t <sub>CE</sub>	Chip Enable Low to Output Valid	$\bar{G} = V_{IL}$		120		150	ns
t <sub>GLQV</sub>	t <sub>OE</sub>	Output Enable Low to Output Valid	$\bar{E} = V_{IL}$		60		80	ns
t <sub>EHQZ</sub> (2)	t <sub>DF</sub>	Chip Enable High to Output Hi-Z	$\bar{G} = V_{IL}$	0	50	0	50	ns
t <sub>GHQZ</sub> (2)	t <sub>DF</sub>	Output Enable High to Output Hi-Z	$\bar{E} = V_{IL}$	0	50	0	50	ns
t <sub>AXQX</sub>	t <sub>OH</sub>	Address Transition to Output Transition	$\bar{E} = V_{IL}, \bar{G} = V_{IL}$	0		0		ns

Note: 1. V<sub>CC</sub> must be applied simultaneously with or before V<sub>PP</sub> and removed simultaneously or after V<sub>PP</sub>.

2. Sampled only, not 100% tested.

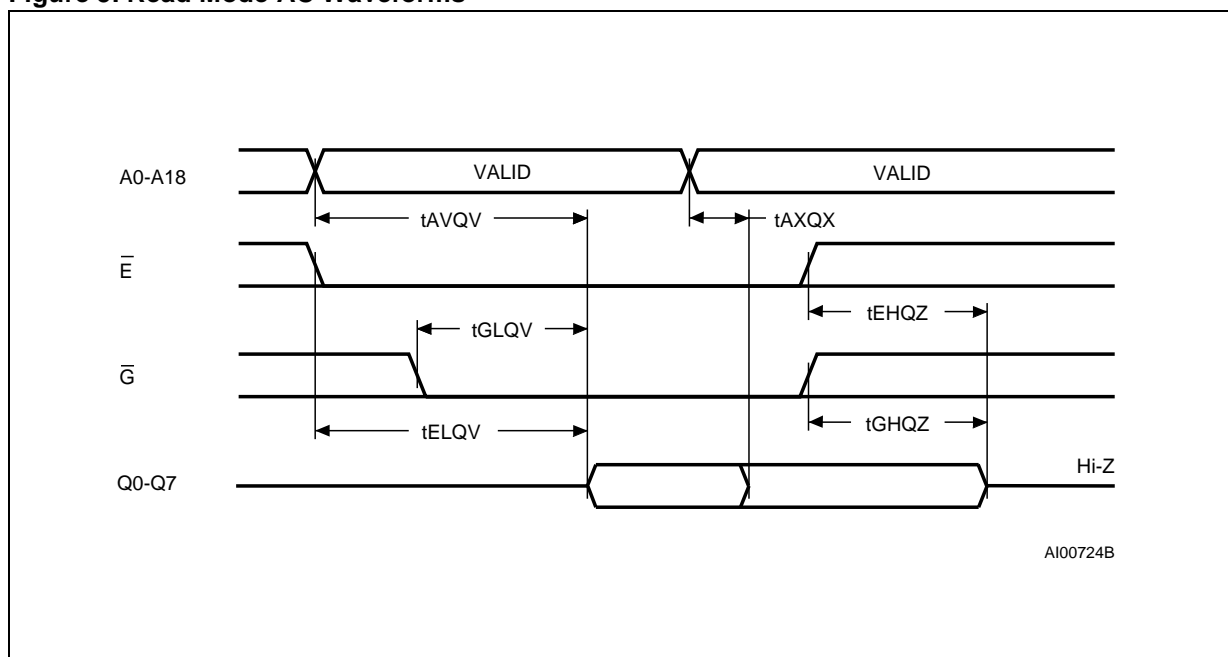
**Table 8B. Read Mode AC Characteristics (1)**

( $T_A = 0$  to  $70^\circ\text{C}$ ,  $-20$  to  $70^\circ\text{C}$ ,  $-20$  to  $85^\circ\text{C}$  or  $-40$  to  $85^\circ\text{C}$ ;  $V_{CC} = 3.3\text{V} \pm 10\%$ ;  $V_{PP} = V_{CC}$ )

Symbol	Alt	Parameter	Test Condition	M27V405				Unit
				-180		-200		
				Min	Max	Min	Max	
$t_{AVQV}$	$t_{ACC}$	Address Valid to Output Valid	$\bar{E} = V_{IL}, \bar{G} = V_{IL}$		180		200	ns
$t_{ELQV}$	$t_{CE}$	Chip Enable Low to Output Valid	$\bar{G} = V_{IL}$		180		200	ns
$t_{GLQV}$	$t_{OE}$	Output Enable Low to Output Valid	$\bar{E} = V_{IL}$		90		100	ns
$t_{EHQZ}^{(2)}$	$t_{DF}$	Chip Enable High to Output Hi-Z	$\bar{G} = V_{IL}$	0	50	0	70	ns
$t_{GHQZ}^{(2)}$	$t_{DF}$	Output Enable High to Output Hi-Z	$\bar{E} = V_{IL}$	0	50	0	70	ns
$t_{AXQX}$	$t_{OH}$	Address Transition to Output Transition	$\bar{E} = V_{IL}, \bar{G} = V_{IL}$	0		0		ns

Note: 1.  $V_{CC}$  must be applied simultaneously with or before  $V_{PP}$  and removed simultaneously or after  $V_{PP}$ .  
 2. Sampled only, not 100% tested

**Figure 5. Read Mode AC Waveforms**



**System Considerations**

The power switching characteristics of Advanced CMOS EPROMs require careful decoupling of the devices. The supply current,  $I_{CC}$ , has three segments that are of interest to the system designer: the standby current level, the active current level, and transient current peaks that are produced by the falling and rising edges of  $\bar{E}$ . The magnitude of the transient current peaks is dependent on the capacitive and inductive loading of the device at the output. The associated transient voltage peaks can be suppressed by complying with the two line

output control and by properly selected decoupling capacitors. It is recommended that a  $0.1\mu\text{F}$  ceramic capacitor be used on every device between  $V_{CC}$  and  $V_{SS}$ . This should be a high frequency capacitor of low inherent inductance and should be placed as close to the device as possible. In addition, a  $4.7\mu\text{F}$  bulk electrolytic capacitor should be used between  $V_{CC}$  and  $V_{SS}$  for every eight devices. The bulk capacitor should be located near the power supply connection point. The purpose of the bulk capacitor is to overcome the voltage drop caused by the inductive effects of PCB traces.

**Table 9. Programming Mode DC Characteristics (1)**  
 ( $T_A = 25\text{ }^\circ\text{C}$ ;  $V_{CC} = 6.25\text{V} \pm 0.25\text{V}$ ;  $V_{PP} = 12.75\text{V} \pm 0.25\text{V}$ )

Symbol	Parameter	Test Condition	Min	Max	Unit
$I_{LI}$	Input Leakage Current	$0 \leq V_{IN} \leq V_{CC}$		$\pm 10$	$\mu\text{A}$
$I_{CC}$	Supply Current			50	mA
$I_{PP}$	Program Current	$\bar{E} = V_{IL}$		50	mA
$V_{IL}$	Input Low Voltage		-0.3	0.8	V
$V_{IH}$	Input High Voltage		2	$V_{CC} + 0.5$	V
$V_{OL}$	Output Low Voltage	$I_{OL} = 2.1\text{mA}$		0.4	V
$V_{OH}$	Output High Voltage TTL	$I_{OH} = -400\mu\text{A}$	2.4		V
$V_{ID}$	A9 Voltage		11.5	12.5	V

Note: 1.  $V_{CC}$  must be applied simultaneously with or before  $V_{PP}$  and removed simultaneously or after  $V_{PP}$ .

**Table 10. Programming Mode AC Characteristics (1)**  
 ( $T_A = 25\text{ }^\circ\text{C}$ ;  $V_{CC} = 6.25\text{V} \pm 0.25\text{V}$ ;  $V_{PP} = 12.75\text{V} \pm 0.25\text{V}$ )

Symbol	Alt	Parameter	Test Condition	Min	Max	Unit
$t_{AVEL}$	$t_{AS}$	Address Valid to Chip Enable Low		2		$\mu\text{s}$
$t_{QVEL}$	$t_{DS}$	Input Valid to Chip Enable Low		2		$\mu\text{s}$
$t_{VPHEL}$	$t_{VPS}$	$V_{PP}$ High to Chip Enable Low		2		$\mu\text{s}$
$t_{VCHEL}$	$t_{VCS}$	$V_{CC}$ High to Chip Enable Low		2		$\mu\text{s}$
$t_{ELEH}$	$t_{PW}$	Chip Enable Program Pulse Width		95	105	$\mu\text{s}$
$t_{EHQX}$	$t_{DH}$	Chip Enable High to Input Transition		2		$\mu\text{s}$
$t_{QXGL}$	$t_{OES}$	Input Transition to Output Enable Low		2		$\mu\text{s}$
$t_{GLQV}$	$t_{OE}$	Output Enable Low to Output Valid			100	ns
$t_{GHQZ}$	$t_{DFP}$	Output Enable High to Output Hi-Z		0	130	ns
$t_{GHAX}$	$t_{AH}$	Output Enable High to Address Transition		0		ns

Note: 1.  $V_{CC}$  must be applied simultaneously with or before  $V_{PP}$  and removed simultaneously or after  $V_{PP}$ .

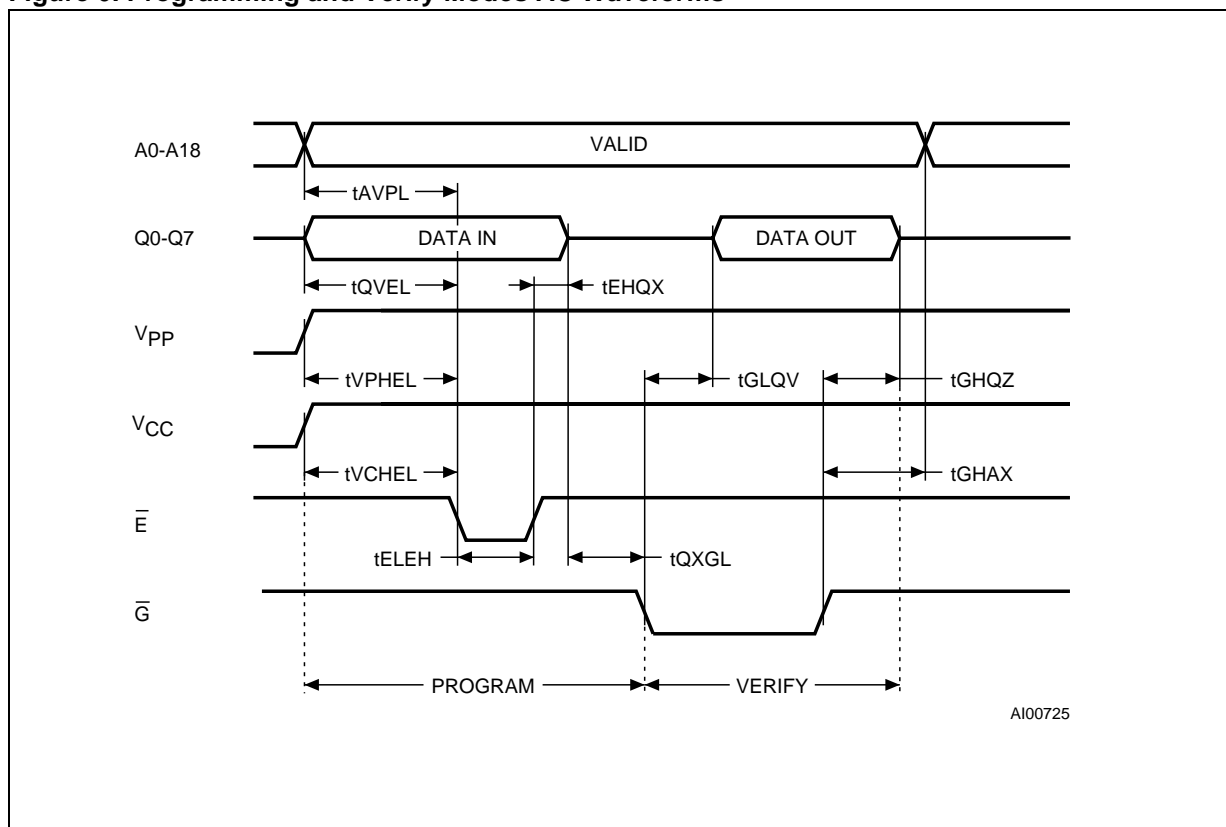
2. Sampled only, not 100% tested.

## Programming

The M27V405 has been designed to be fully compatible with the M27C405 and has the same electronic signature. As a result the M27V405 can be programmed as the M27C405 on the same programming equipments applying 12.75V on  $V_{PP}$  and 6.25V on  $V_{CC}$  by the use of the same PRES-TO II algorithm. When delivered, all bits of the M27V405 are in the '1' state. Data is introduced by selectively programming '0's into the desired bit lo-

cations. Although only '0's will be programmed, both '1's and '0's can be present in the data word. The M27V405 is in the programming mode when  $V_{PP}$  input is at 12.75V,  $\bar{G}$  is at  $V_{IH}$  and  $\bar{E}$  is pulsed to  $V_{IL}$ . The data to be programmed is applied to 8 bits in parallel to the data output pins. The levels required for the address and data inputs are TTL.  $V_{CC}$  is specified to be  $6.25\text{V} \pm 0.25\text{V}$ , but it can be set to lower values in case of On-Board Programming (see dedicated paragraph).

Figure 6. Programming and Verify Modes AC Waveforms



### PRESTO II Programming Algorithm

PRESTO II Programming Algorithm allows the whole array to be programmed with a guaranteed margin, in a typical time of 52.5 seconds. Programming with PRESTO II consists of applying a sequence of 100 $\mu$ s program pulses to each byte until a correct verify occurs (see Figure 7). During programming and verify operation, a MARGIN MODE circuit is automatically activated in order to guarantee that each cell is programmed with enough margin. No overprogram pulse is applied since the verify in MARGIN MODE provides the necessary margin to each programmed cell.

### Program Inhibit

Programming of multiple M27V405s in parallel with different data is also easily accomplished. Except for E-bar, all like inputs including G-bar of the parallel M27V405 may be common. A TTL low level pulse applied to a M27V405's E-bar input, with V<sub>PP</sub> at 12.75V, will program that M27V405. A high level E-bar input inhibits the other M27V405s from being programmed.

### Program Verify

A verify (read) should be performed on the programmed bits to determine that they were correctly programmed. The verify is accomplished with G-bar at V<sub>IL</sub>, E-bar at V<sub>IH</sub>, V<sub>PP</sub> at 12.75V and V<sub>CC</sub> at 6.25V.

### On-Board Programming

Programming the M27V405 may be performed directly in the application circuit, however this requires modification to the PRESTO II Algorithm (see Figure 8). For in-circuit programming V<sub>CC</sub> is determined by the user and normally is compatible with other components using the same supply voltage. It is recommended that the maximum value of V<sub>CC</sub> which remains compatible with the circuit is used.

Typically V<sub>CC</sub> = 5.5V for programming systems using V<sub>CC</sub> = 5V, and V<sub>CC</sub> = 3.5V for low voltage 3V systems is recommended. The value of V<sub>CC</sub> does not affect the programming, it gives a higher test capability in VERIFY mode.

V<sub>PP</sub> must be kept at 12.75 volts to maintain and enable the programming.



Figure 7. Programming Flowchart

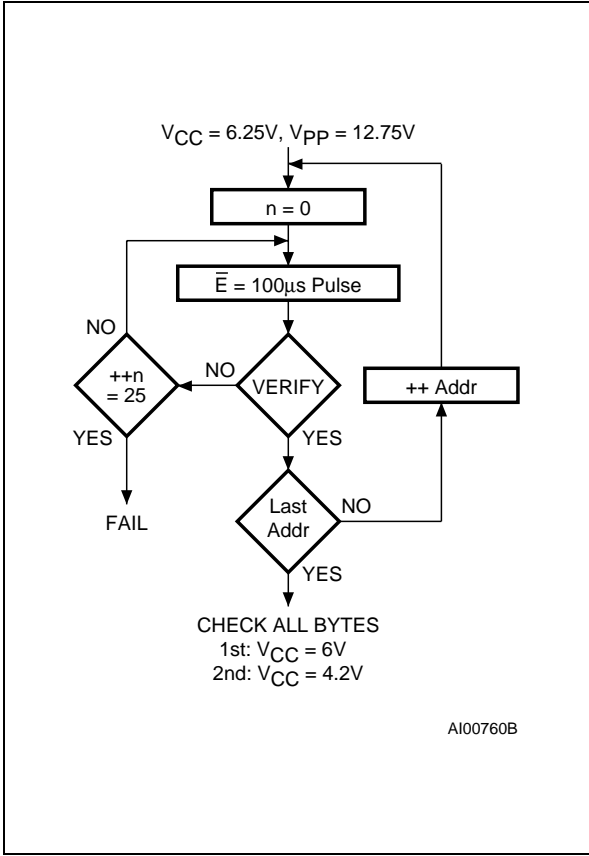
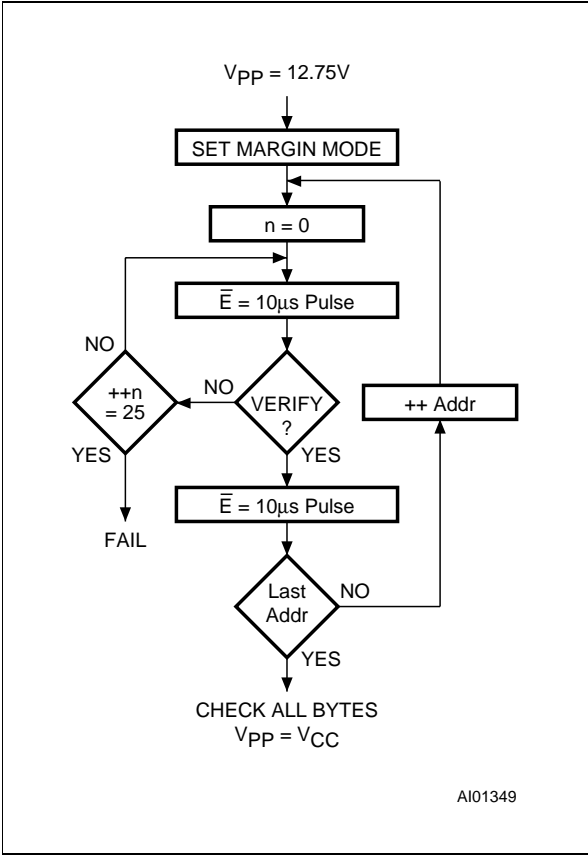


Figure 8. On-Board Programming Flowchart



**Warning: compatibility with Flash Memory**

Compatibility issues may arise when replacing the compatible Single Supply 4 Mbit Flash Memory (the M29F040) by the M27V405.

The VPP pin of the M27V405 corresponds to the "W" pin of the M29F040. The M27V405 VPP pin can withstand voltages up to 12.75V, while the "W" pin of the M29F040 is a normal control signal input and may be damaged if a high voltage is applied; special precautions must be taken when programming in-circuit.

However if an already programmed M27V405 is used, this can be directly put in place of the Flash Memory as the VPP input, when not in programming mode, is set to VCC or VSS.

**Changes to PRESTO II.** The duration of the programming pulse is reduced to 20µs, making the programming time of the M27V405 comparable with the counterpart Flash Memory.

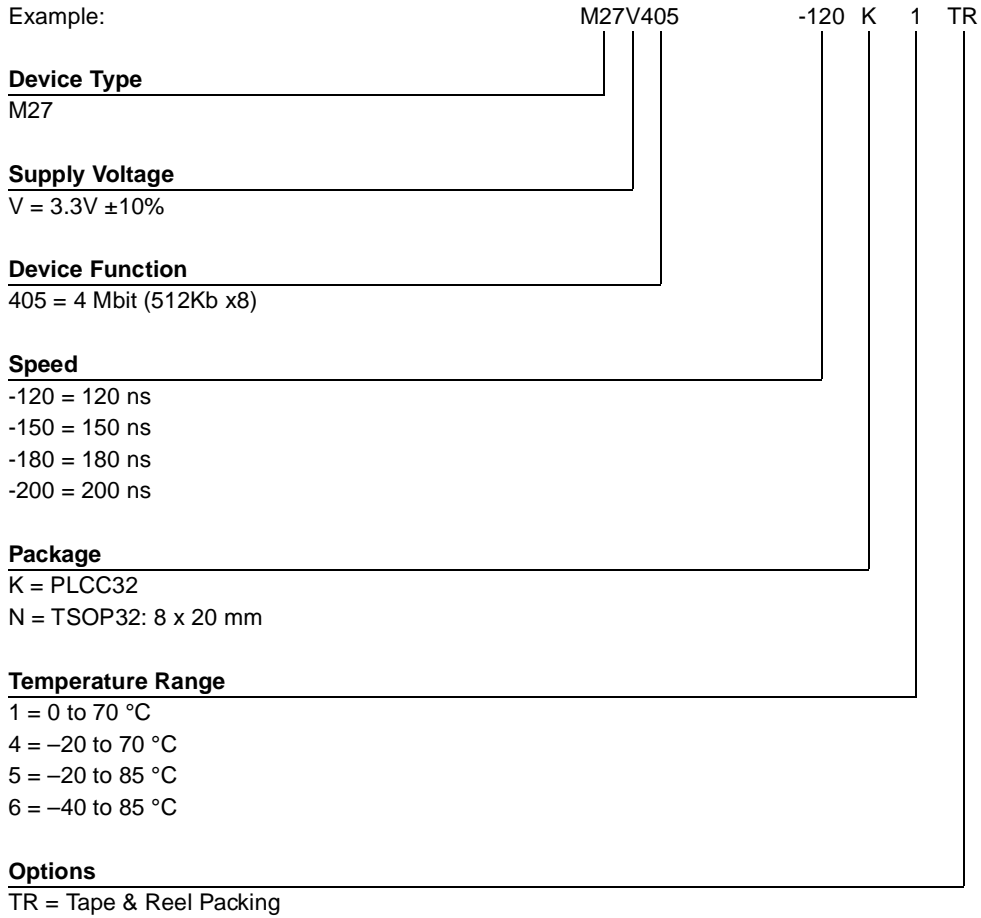
**Electronic Signature**

The Electronic Signature (ES) mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and type. This mode is intended for use by programming equipment to automatically match the device to be programmed with its corresponding programming algorithm. This mode is functional in the 25°C ± 5°C ambient temperature range that is required when programming the M27V405. To activate the ES mode, the programming equipment must force 11.5V to 12.5V on address line A9 of the M27V405 with VPP = VCC = 5V. Two identifier bytes may then be sequenced from the device outputs by toggling address line A0 from VIL to VIH. All other address lines must be held at VIL during Electronic Signature mode. Byte 0 (A0 = VIL) represents the manufacturer code and byte 1 (A0 = VIH) the device identifier code. For the STMicroelectronics M27V405, these two identifier bytes are given in Table 4 and can be read-out on outputs Q7 to Q0.

## M27V405

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**Table 11. Ordering Information Scheme**

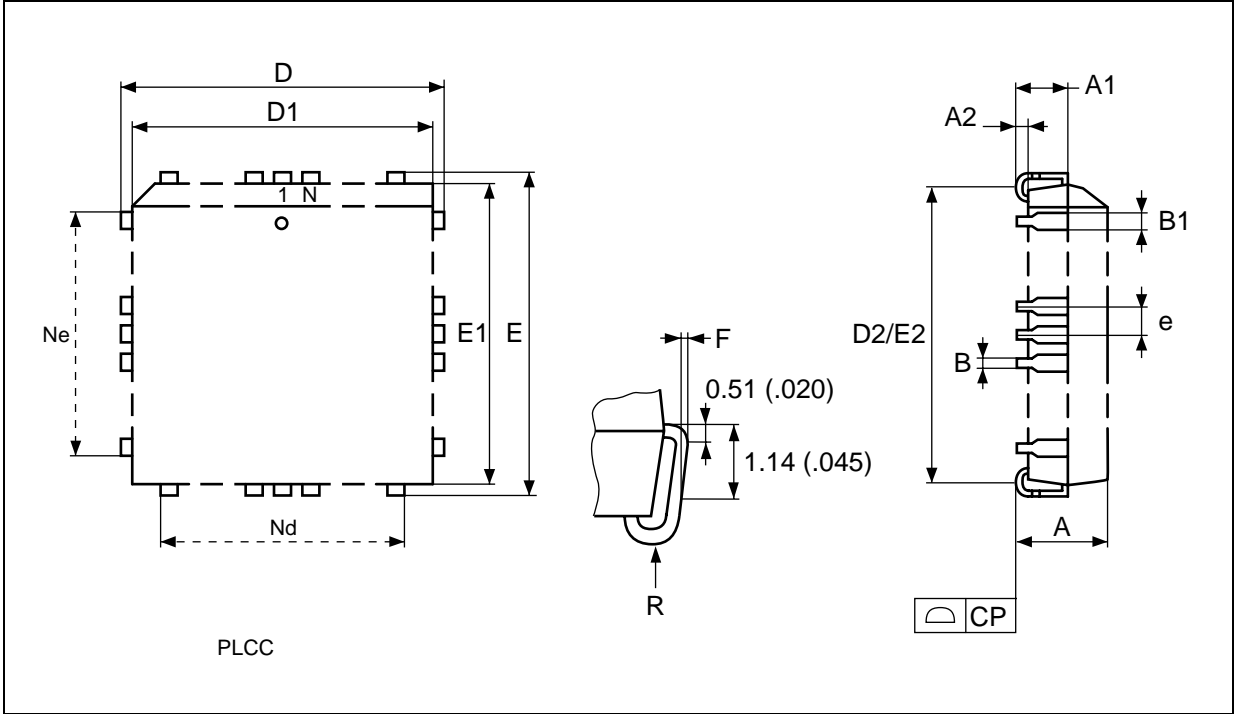


For a list of available options (Speed, Package, etc...) or for further information on any aspect of this device, please contact the STMicroelectronics Sales Office nearest to you.

Table 12. PLCC32 - 32 lead Plastic Leaded Chip Carrier, Package Mechanical Data

Symb	mm			inches		
	Typ	Min	Max	Typ	Min	Max
A		2.54	3.56		0.100	0.140
A1		1.52	2.41		0.060	0.095
A2		0.38	–		0.015	–
B		0.33	0.53		0.013	0.021
B1		0.66	0.81		0.026	0.032
D		12.32	12.57		0.485	0.495
D1		11.35	11.56		0.447	0.455
D2		9.91	10.92		0.390	0.430
E		14.86	15.11		0.585	0.595
E1		13.89	14.10		0.547	0.555
E2		12.45	13.46		0.490	0.530
e	1.27	–	–	0.050	–	–
F		0.00	0.25		0.000	0.010
R	0.89	–	–	0.035	–	–
N		32			32	
Nd		7			7	
Ne		9			9	
CP			0.10			0.004

Figure 9. PLCC32 - 32 lead Plastic Leaded Chip Carrier, Package Outline

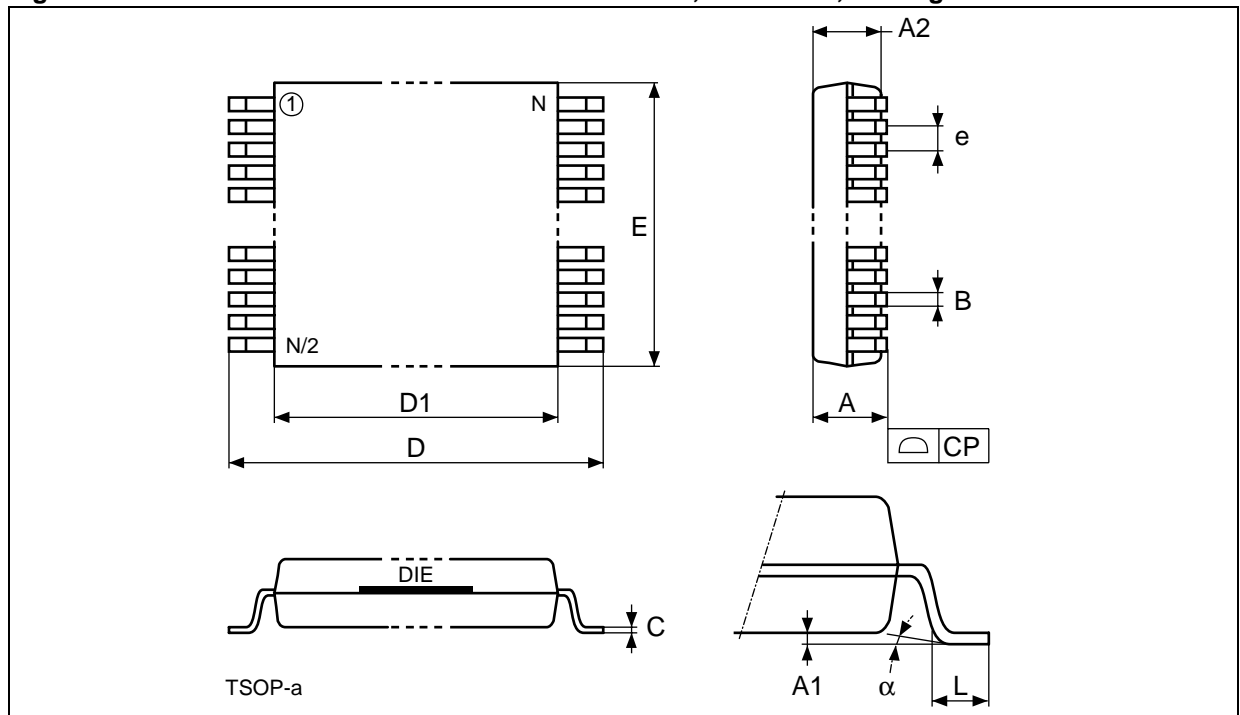


Drawing is not to scale.

Table 13. TSOP32 - 32 lead Plastic Thin Small Outline, 8 x 20 mm, Package Mechanical Data

Symb	mm			inches		
	Typ	Min	Max	Typ	Min	Max
A			1.20			0.047
A1		0.05	0.15		0.002	0.007
A2		0.95	1.05		0.037	0.041
B		0.15	0.27		0.006	0.011
C		0.10	0.21		0.004	0.008
D		19.80	20.20		0.780	0.795
D1		18.30	18.50		0.720	0.728
E		7.90	8.10		0.311	0.319
e	0.50	-	-	0.020	-	-
L		0.50	0.70		0.020	0.028
$\alpha$		0°	5°		0°	5°
N	32			32		
CP			0.10			0.004

Figure 10. TSOP32 - 32 lead Plastic Thin Small Outline, 8 x 20 mm, Package Outline



Drawing is not to scale.

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